Subsystem		Specification	Current Results	Date Measured	Comments				
Imaging			1		-1	1 1	1	1	ļ. ļ.
CD uniformity				N/A	No lens qual	measured prior to	shutdown		
	-				-				
Illumination and Dose control		1	1	1	1			,	1
Slit uniformity	Setting 1	NA=0.85			Annular, Si=	0.69,So=0.93			
	Intensity	>1000mW	1023.22	2012-09-09	LUSU.99				
	Slit Uniformity	<0.35%	0.25	2012-09-09					
	Scan Uniformity	<0.2%							
	Setting 2	NA=0.70			Annular, Si=	0.45, So=0.75			
	Intensity	>1130mW	N/A						
	setting 3	NA=0.85			Annular, Si=	0.58,So=0.88			
	Intensity	>1130mW	N/A						
Dose System Performance	Setting1	<1.4%	1.343	2012-09-09	ODDP.99				
Dose Repeatability and Accuracy	Setting 1							1	
	Repeatability	<0.4%	0.127	2011-12-27	ODAR.67			1	
	Accuracy	<1.5%	0.377	2011-12-27	ODAR.67			1	
Pupil Verification	Setting 1								
	Ellipticity	<3.0%	2.25	2012-07-07	LUPI.99				
	Sigma Variation	<0.012%	0.003	2012-07-07	LUPI.99				
	Sigma Repro	< 0.005	N/A						
Projection	10	1		1	ļ	1 1	1	1	1
Aberrations	RMS z5-Z37	<1.8nm	0.16	2012-09-09	EMZC.50				
	RMS spherical	<1.0nm	0.23	2012-09-09	EMZC.50				
	RMS coma	<1.0nm	0.03	2012-09-09	EMZC.50				
	RMS astigmatism	<1.0nm	0	2012-09-09	EMZC.50				
Non-correctable distortion setting1	NCE	<8.0nm	N/A						
Image plane deviation @ 70nm setting1	IPD	<55nm	207	2012-04-04	EPSO.11 - Do	on't know if this da	ita is reliable	e as it is onl	y exposed on one chuck
Astigmatism @ 70nm setting 1	Ast	<35	124	2012-04-04					y exposed on one chuck
Long Range Stray light setting 1	Max	<1.0	0.74	2012-09-09	EMCA.95				
Short Range Stray light setting 1	Max	<1.5	N/A	2012 05 05	21110/ 1.33				
Focus and Levelling	ITTUK	11.5	,,,						
Wafer Map reproducibility	99.70%	<15nm	5.8	2006-08-20	EMWA.01				
Full wafer focus uniformity	55.7678	<15nm	5.0	2000 00 20		1	1		
Chuck to Chuck Focus difference		<60nm	N/A		No data sy	stem ran dual chu	ck mode		
Focus stability		<40nm	N/A			ed prior to shut do			
Dynamic Performance		(Tohin	,,,		inter incusure				
Moving standard deviation	mean +3sig	<7.0nm	5	2012-09-08	TSDA.16				
Moving average	mean +3sig	<3.0nm	0.8	2012-09-08	TSDA.16				
Reticle Masking Accuracy	incan (55)g	<300um	N/A	2012 05 00	1304.10	1	1	1	1
Overlay		Sooum	177		1	I I			
Stage Repeatability		<4.0nm	0	XYWO.06	9/3/2011 - r	epeatability value	0 0 not sure	if accurate	
Stage grid verification		<4.0nm	8.5	FGG0.02	2007-02-26				
Single Machine Overlay	overlay max 99.7%	<7.0nm	4.5,3.3nm	XYNO.23	2007-02-20				
Matched Machine Overlay	overlay max 99.7%	<14.0	3.5,2.9nm	X1N0.23 XYMO.68	2003-01-10				
Productivity	54CHay Hlax 33.770	14.0	5.5,2.31111	7110.00	2012-09-14			1	
Throughput	wafer/hour	>150w/hr	N/A		no recent da	ta			
IIIIOugiput	water/noui	>130W/III	IN/A		no recent ua	itu -		1	

Subsystem	1	Specification	Current Results	Date Measured	Comments		
	Reticle Exchange Time	<13s	N/A		no recent data		
	Lot Overhead	<13s	N/A		no recent data		
Reticle Ma	isking Accuracy						
					no recent data		